# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**

[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>Name / Model #1</th>
<th>Name / Model #2</th>
<th>Name / Model #3</th>
<th>Name / Model #4</th>
<th>Name / Model #5</th>
</tr>
</thead>
<tbody>
<tr>
<td>HP G72</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Motherboard, Touch pad</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Coin cell battery, Battery pack</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>Screw driver</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble main battery
2. Disassemble ram door & hdd door screw*4(M2.5*6)
3. Disassemble HDD screw*4(M2.5*4) & Pull out HDD Module
4. Dis-fasten Base screw(M2.5*9-2 pcs,M2.5*4-4pcs,M2.5*6-14pcs)
5. Disassemble WLAN module screw*1(M2*3)
6. Remove WLAN
7. Pull out RTC Battery cable, DC-IN cable & ODD Module
8. Remove RAM
9. Disassemble Keyboard module
10. Remove keyboard membrane
11. Pull out Speaker Cable, Disassemble Power FFC,TP FFC & TP Switch FFC
12. Dis-fasten KB Deck Plate screw*4(M2.5*6)
13. Disassemble KB Deck
14. Disassemble speaker module screw*2(M2*6)
15. Remove speaker module
16. Disassemble TP bracket*4 (M2*3)
17. Pull out LVDS cable, Mic cable, ODD cable, Bluetooth cable, USB FFC
18. Disassemble Modem card screw*2 (M2*3)
19. Disassemble mainboard screw*3(M2.5*6)
20. Disassemble FAN module screw*1(M2.5*6)
21. Remove mainboard
22. Dis-fasten hinge base screw*4 (M2.5*6)
23. Remove Display cover module
24. Remove display cover screw cover
25. Dis-fasten screw cover screw*2(M2.5*4)
26. Disassemble LCD Bezel
27. Dis-fasten hinge cap screw*2 (M2.5*5)
28. Remove hinge cap
29. Dis-fasten LCD module screw*8 (M2.5*5)
30. Disassemble LCD cable and camera module cable.
31. Remove LCD Module
32. Dis-fasten LCD hinge bracket screw*6 (M2*3)
33. Remove LCD panel
34. Dis-fasten FAN module screw from mainboard
35. Remove FAN module
36. Remove CPU
37. Remove CPU bracket
38. Remove GPU bracket
39.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).